



# 1.1MHz, Precision, Rail-to-Rail I/O CMOS Operational Amplifier

#### 1 FEATURES

• High Gain Bandwidth: 1.1MHz

Rail-to-Rail Input and Output
 0.5mV Max Vos

 Input Voltage Range: -0.2V to +5.7V with Vs = 5.5V

• Supply Range: +2.1V to +5.5V

Specified Up to +125°C

• Micro Size Packages: SOT23-5, SC70-5

#### **2 APPLICATIONS**

- Sensors
- Photodiode Amplification
- Active Filters
- Test Equipment
- Driving A/D Converters

#### **3 DESCRIPTIONS**

The RS321BP products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth (1.1MHz) and slew rate of  $0.5V/\mu s$ . The op-amps are unity gain stable and feature an ultra-low input bias current.

The RS321BP has lower offset, which is guaranteed not upper than 0.5mV at 25°C with  $V_s=5V$ ,  $V_{CM}=V_s/2$ .

The devices are ideal for sensor interfaces, active filters and portable applications. The RS321BP operational amplifiers are specified at the full temperature range of -40°C to 125°C under single supplies of 2.1V to 5.5V or dual power supplies of ±1.05V to ±2.75V.

#### Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE(NOM)		
RS321BP	SOT23-5	2.90mm×1.60mm		
	SC70-5	2.10mm×1.25mm		

<sup>(1)</sup> For all available packages, see the orderable addendum at the end of the data sheet.



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## **4 REVISION HISTORY**

Note: Page numbers for previous revisions may different from page numbers in the current version.

Version	Change Date	Change Item
A.1	2022/05/25	Initial version completed
A.1.1	2024/03/05	Modify packaging naming
A.2	2024/12/13	<ol> <li>Add REVISION HISTORY</li> <li>Add MSL on Page 4 in RevA.1.1</li> <li>Add Package thermal impedance on Page 3 in RevA.1.1</li> <li>Update PACKAGE note</li> <li>Add TAPE AND REEL INFORMATION</li> <li>Delete RS321PXF/RS321PXC5 Orderable Device</li> <li>Delete content related to RS321P</li> <li>Change the product name to: RS321BP</li> </ol>



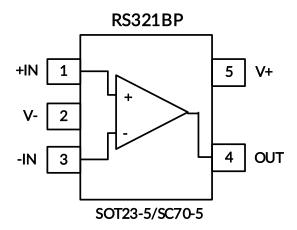
## **5 PACKAGE/ORDERING INFORMATION (1)**

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking <sup>(2)</sup>	MSL (3)	Package Qty
RS321BPXF	SOT23-5	5	1	-40°C ~125°C	321BP	MSL3	Tape and Reel, 3000
RS321BPXC5	SC70-5 (4)	5	1	-40°C ~125°C	321BP	MSL3	Tape and Reel, 3000

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) RUNIC classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F. Please align with RUNIC if your end application is quite critical to the preconditioning setting or if you have special requirement.
- (4) Equivalent to SOT353.



## **6 PIN CONFIGURATION AND FUNCTIONS**



#### **PIN DESCRIPTION**

	PIN					
NAME	NAME RS321BP I/O		DESCRIPTION			
	SOT23-5/SC70-5					
-IN	3	I	Negative (inverting) input			
+IN	1	I	Positive (noninverting) input			
OUT	4	0	Output			
V-	2	-	Negative (lowest) power supply			
V+	5	-	Positive (highest) power supply			

<sup>(1)</sup> I = Input, O = Output.



#### **7 SPECIFICATIONS**

#### 7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT	
	Supply, V <sub>S</sub> =(V+) - (V-)		7			
Voltage	Signal input pin <sup>(2)</sup>		(V-)-0.5	(V+) +0.5	V	
	Signal output pin (3)	(V-)-0.5	(V+) +0.5			
	Signal input pin <sup>(2)</sup>	-10	10	mA		
Current	Signal output pin <sup>(3)</sup>	-140 140		mA		
	Output short-circuit (4)	Conti				
	D1 (5)	SOT23-5		230	9C /\\	
θια	Package thermal impedance (5) SC70-5			380	°C/W	
	Operating range, T <sub>A</sub>	-40	125			
Temperature	Junction, T <sub>J</sub> <sup>(6)</sup>		150	°C		
	Storage, T <sub>stg</sub>	-65	150			

<sup>(1)</sup> Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.
- (3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ±140mA or less.
- (4) Short-circuit to ground, one amplifier per package.
- (5) The package thermal impedance is calculated in accordance with JESD-51.
- (6) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $R_{\theta JA}$ , and  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} T_A) / R_{\theta JA}$ . All numbers apply for packages soldered directly onto a PCB.

#### 7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT	
\/	Flactuactatic discharge	Human-Body Model (HBM)			
V <sub>(ESD)</sub> Electrostatic discharge	Machine Model (MM)	±200	V		



#### **ESD SENSITIVITY CAUTION**

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### 7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>S</sub> = (V+) - (V-)	Single-supply	2.1		5.5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
	Dual-supply	±1.05		±2.75	\ \ \
Specified temperature	ecified temperature			125	°C



## 7.4 Electrical Characteristics

 $\underline{(\text{At T}_{\text{A}} = +25^{\circ}\text{C}, \text{V}_{\text{S}} = 5\text{V}, \text{R}_{\text{L}} = 10\text{k}\Omega \text{ connected to } \text{V}_{\text{S}}/2, \text{and } \text{V}_{\text{OUT}} = \text{V}_{\text{S}}/2, \text{Full} \overset{(9)}{=} -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}, \text{ unless otherwise noted.})}{}^{(1)}$ 

	DADAN4FTFD	DADAMETED CONDITIONS T		RS321BP			
	PARAMETER	CONDITIONS	T,	MIN <sup>(2)</sup>	<b>TYP</b> (3)	MAX <sup>(2)</sup>	UNITS
POWER	SUPPLY		•	•			
Vs	Operating Voltage Range		25°C	2.1		5.5	V
Ιq	Quiescent Current		25°C		85	150	μΑ
DCDD	D C   D : 1: D !:	V <sub>S</sub> =2.1V to 5.5V,	25°C	72	90		ū
PSRR	Power-Supply Rejection Ratio	V <sub>CM</sub> =(V-)+0.5V	Full	64			dB
ton	Turn-on time	V <sub>S</sub> = 5V			25		μs
INPUT			<u>.</u>				
Vos	Input Offset Voltage	RS321BP	25°C	-0.5	±0.2	0.5	mV
Vos Tc	Input Offset Voltage Average Drift		Full		2		μV/°C
IB	Input Bias Current (4) (5)		25°C		1	10	pА
los	Input Offset Current (4)		25°C		1	10	pА
Vcm	Common-Mode Voltage Range	V <sub>S</sub> = 5.5V	25°C	-0.2		5.7	V
		V <sub>S</sub> = 5.5V,	25°C	71	92		dB
CMRR Common-Mode Rejection Ratio		V <sub>CM</sub> =-0.2V to 4V	Full	65			
	Common-Mode Rejection Ratio	V <sub>S</sub> = 5.5V,	25°C	61	83		
		V <sub>CM</sub> =-0.2V to 5.7V	Full	57			
OUTPUT	<u> </u>						
		$R_L=2k\Omega$ ,	25°C	93	105		
^		Vo=0.15V to 4.85V	Full	83			dB
Aol	Open-Loop Voltage Gain	R <sub>L</sub> =10kΩ,	25°C	100	110		
		Vo= 0.05V to 4.95V	Full	92			
	0 + +6 : (	R <sub>L</sub> =2kΩ	0506		25		
	Output Swing from Rail	R <sub>L</sub> =10kΩ	25°C		8		mV
lout	Output Short-Circuit Current (6) (7)		25°C		110		mA
FREQUE	NCY RESPONSE						
SR	Slew Rate (8)	C <sub>L</sub> =100pF, G=1	25°C		0.5		V/µs
GBP	Gain-Bandwidth Product		25°C		1.1		MHz
PM	Phase Margin		25°C		64		0
ts	Settling Time, 0.1%	C <sub>L</sub> =100pF, Vs=5V, 2-V step, G=1			6.5		μs
	Overload Recovery Time	V <sub>IN</sub> ∙Gain≥V <sub>S</sub>			4		μs
NOISE							
	Input Voltage Noise Density	f = 1kHz	25°C		22		nV/√Hz
en	input voitage noise Density	f = 10kHz	25°C		20		nV/√Hz



- (1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.
- (4) This parameter is ensured by design and/or characterization and is not tested in production.
- (5) Positive current corresponds to current flowing into the device.
- (6) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $R_{\theta JA}$ , and  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} T_A) / R_{\theta JA}$ . All numbers apply for packages soldered directly onto a PCB.
- (7) Short circuit test is a momentary test.
- (8) Number specified is the slower of positive and negative slew rates.
- (9) Specified by characterization only.



### 7.5 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At  $T_A$  = +25°C,  $V_S$ =5V,  $R_L$  = 10k $\Omega$  connected to  $V_S/2$ ,  $V_{OUT}$  =  $V_S/2$ , unless otherwise noted.

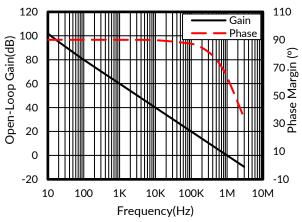


Figure 1. Open-Loop Gain and Phase vs Frequency

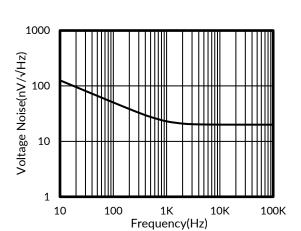


Figure 3. Input Voltage Noise Spectral Density vs Frequency

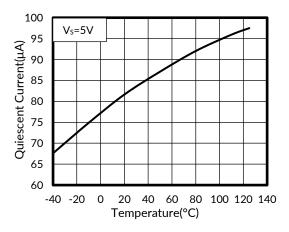


Figure 5. Quiescent Current vs Temperature

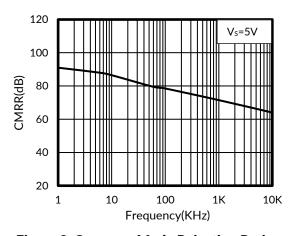


Figure 2. Common-Mode Rejection Ratio vs Frequency

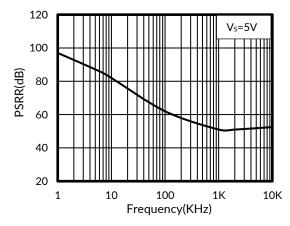


Figure 4. Power-Supply Rejection Ratio vs Frequency

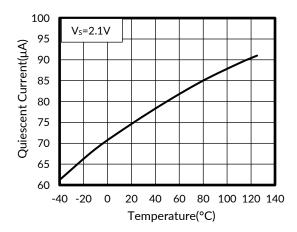


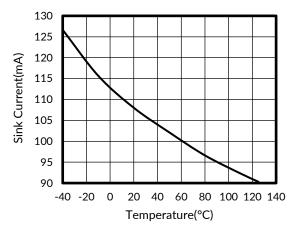
Figure 6. Quiescent Current vs Temperature



## **Typical Characteristics**

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At  $T_A$  = +25°C,  $V_S$ =5V,  $R_L$  = 10k $\Omega$  connected to  $V_S/2$ ,  $V_{OUT}$  =  $V_S/2$ , unless otherwise noted.



**Figure 7. Sink Current vs Temperature** 

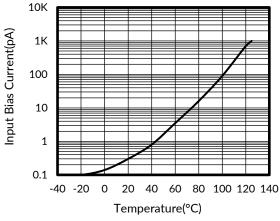


Figure 9. Input Bias Current vs Temperature

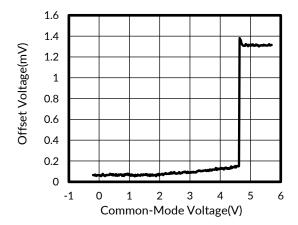
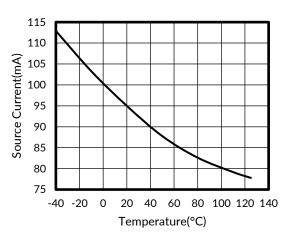


Figure 11. Offset Voltage vs Common-Mode Voltage



**Figure 8. Source Current vs Temperature** 

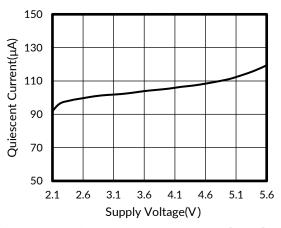


Figure 10. Quiescent Current vs Supply Voltage

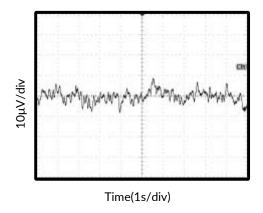


Figure 12. 0.1Hz to 10Hz Input Voltage Noise



## **Typical Characteristics**

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At  $T_A$  = +25°C,  $V_S$ =5V,  $R_L$  = 10k $\Omega$  connected to  $V_S/2$ ,  $V_{OUT}$  =  $V_S/2$ , unless otherwise noted.

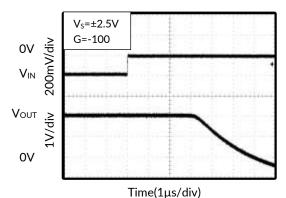


Figure 13. Positive Overvoltage Recovery

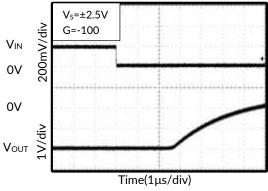


Figure 14. Negative Overvoltage Recovery

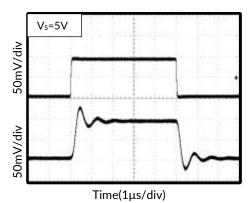


Figure 15. Small-Signal Step Response

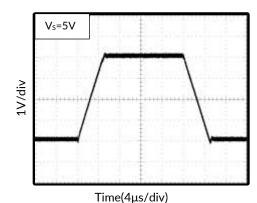


Figure 16. Large-Signal Step Response

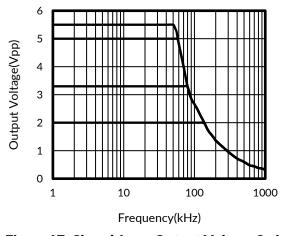


Figure 17. Closed-Loop Output Voltage Swing

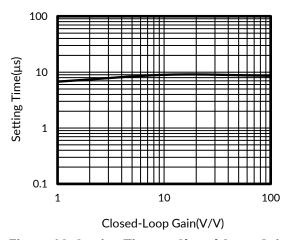


Figure 18. Setting Time vs Closed-Loop Gain



#### **8 DETAILED DESCRIPTION**

#### 8.1 Overview

The RS321BP devices are unity-gain stable, single-channel op amps with low noise and distortion. The device consists of a low noise input stage with a folded cascade and a rail-to-rail output stage. This topology exhibits superior noise and distortion performance across a wide range of supply voltages that are not delivered by legacy commodity audio operational amplifiers.

#### 8.2 Phase Reversal Protection

The RS321BP has internal phase-reversal protection. Many op amps exhibit phase reversal when the input is driven beyond the linear common-mode range. This condition is most often encountered in noninverting circuits when the input is driven beyond the specified common-mode voltage range, causing the output to reverse into the opposite rail. The input of the RS321BP prevents phase reversal with excessive common-mode voltage. Instead, the appropriate rail limits the output voltage. This performance is shown in figure 19.

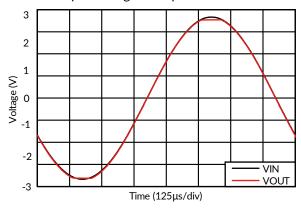


Figure 19. Output Waveform Devoid of Phase Reversal During an Input Overdrive Condition

#### 8.3 EMI Rejection Ratio (EMIRR)

The electromagnetic interference (EMI) rejection ratio, or EMIRR, describes the EMI immunity of operational amplifiers. An adverse effect that is common to many operational amplifiers is a change in the offset voltage as a result of RF signal rectification. An operational amplifier that is more efficient at rejecting this change in offset as a result of EMI has a higher EMIRR and is quantified by a decibel value. Measuring EMIRR can be performed in many ways, but this document provides the EMIRR IN+, which specifically describes the EMIRR performance when the RF signal is applied to the noninverting input pin of the operational amplifier. In general, only the noninverting input is tested for EMIRR for the following three reasons:

- Operational amplifier input pins are known to be the most sensitive to EMI, and typically rectify RF signals better than the supply or output pins.
- The noninverting and inverting operational amplifier inputs have symmetrical physical layouts and exhibit nearly matching EMIRR performance.
- EMIRR is easier to measure on noninverting pins than on other pins because the noninverting input pin can be isolated on a printed-circuit-board (PCB). This isolation allows the RF signal to be applied directly to the noninverting input pin with no complex interactions from other components or connecting PCB traces.



### **DETAILED DESCRIPTION (continued)**

The EMIRR IN+ of the RS321BP is plotted versus frequency in Figure 20. If available, any dual and quad operational amplifier device versions have approximately identical EMIRR IN+ performance. The RS321BP unity-gain bandwidth is 1.1MHz. EMIRR performance below this frequency denotes interfering signals that fall within the operational amplifier bandwidth.

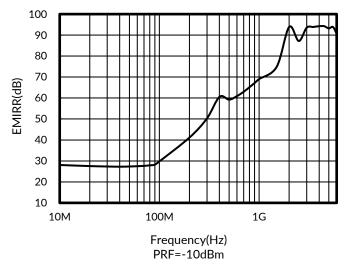


Figure 20. RS321BP EMIRR vs Frequency

#### 8.4 EMIRR IN+ Test Configuration

Figure 21 shows the circuit configuration for testing the EMIRR IN+. An RF source is connected to the operational amplifier noninverting input pin using a transmission line. The operational amplifier is configured in a unity-gain buffer topology with the output connected to a low-pass filter (LPF) and a digital multimeter (DMM). A large impedance mismatch at the operational amplifier input causes a voltage reflection; however, this effect is characterized and accounted for when determining the EMIRR IN+. The resulting dc offset voltage is sampled and measured by the multimeter. The LPF isolates the multimeter from residual RF signals that can interfere with multimeter accuracy.

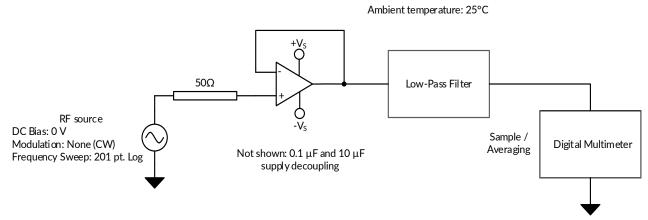


Figure 21. EMIRR IN+ Test Configuration Schematic



#### 9 APPLICATION AND IMPLEMENTATION

Information in the following applications sections is not part of the RUNIC component specification, and RUNIC does not warrant its accuracy or completeness. RUNIC's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### 9.1 Application Note

The RS321BP are high precision, rail-to-rail operational amplifiers that can be run from a single-supply voltage 2.1V to 5.5V ( $\pm 1.05$ V to  $\pm 2.75$ V). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier. Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Good layout practice mandates use of a  $0.1\mu$ F capacitor place closely across the supply pins.

## Typical Applications 9.2 25-kHz Low-Pass Filter

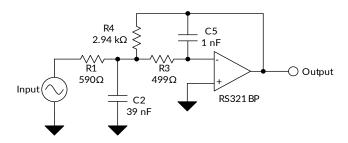


Figure 22. 25-kHz Low-Pass Filter

#### 9.3 Design Requirements

Low-pass filters are commonly employed in signal processing applications to reduce noise and prevent aliasing. The RS321BP devices are ideally suited to construct high-speed, high-precision active filters. Figure 22 shows a second-order, low-pass filter commonly encountered in signal processing applications.

Use the following parameters for this design example:

- Gain = 5 V/V (inverting gain)
- Low-pass cutoff frequency = 25 kHz
- Second-order Chebyshev filter response with 3-dB gain peaking in the passband

#### 9.4 Detailed Design Procedure

The infinite-gain multiple-feedback circuit for a low-pass network function is shown in Figure 22. Use Equation 1 to calculate the voltage transfer function.

$$\frac{\text{Output}}{\text{Input}}(s) = \frac{-1/R_1R_3C_2C_5}{s^2 + (s/C_2) + (1/R_1 + 1/R_3 + 1/R_4) + 1/R_3R_4C_2C_5}$$
(1)

This circuit produces a signal inversion. For this circuit, the gain at dc and the low-pass cutoff frequency are calculated by Equation 2:

Gain = 
$$\frac{R_4}{R_1}$$
  
 $f_c = \frac{1}{2\pi} \sqrt{(1/R_3 R_4 C_2 C_5)}$  (2)



## 9.5 Application Curve

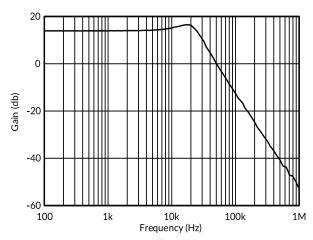
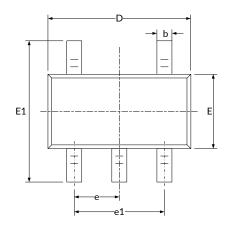
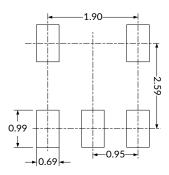


Figure 23. Low-Pass Filter Transfer Function

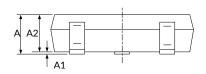


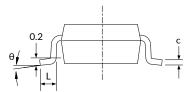
## 10 PACKAGE OUTLINE DIMENSIONS SOT23-5 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



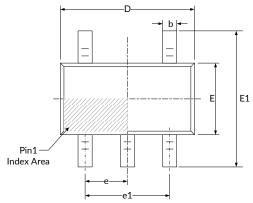


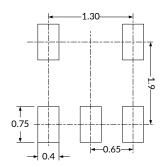
C. mah al	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A (1)	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D (1)	2.820	3.020	0.111	0.119	
E (1)	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(	BSC) (2)	0.037(	BSC) (2)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
   This drawing is subject to change without notice.

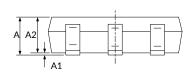


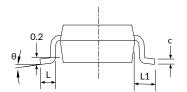
## SC70-5 (3)





RECOMMENDED LAND PATTERN (Unit: mm)





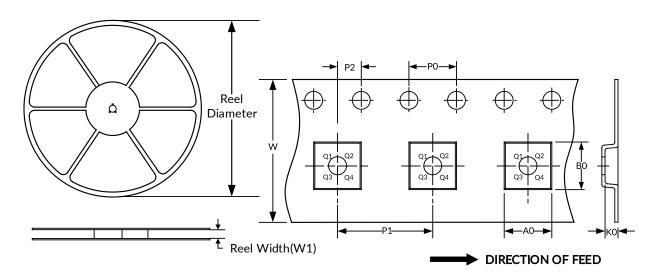
Complete	Dimensions I	n Millimeters	Dimension	s In Inches	
Symbol	Min	Max	Min	Max	
A (1)	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.080	0.150	0.003	0.006	
D (1)	2.000	2.200	0.079	0.087	
E (1)	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
e	0.650(	BSC) (2)	0.026(	BSC) (2)	
e1	1.300(	BSC) (2)	0.051(	BSC) (2)	
L	0.260	0.460	0.010	0.018	
L1	0.5	525	0.021		
θ	0°	8°	0°	8°	

- 1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
- 2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.3. This drawing is subject to change without notice.



## 11 TAPE AND REEL INFORMATION REEL DIMENSIONS

#### **TAPE DIMENSION**



NOTE: The picture is only for reference. Please make the object as the standard.

#### **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SC70-5	7"	9.5	2.25	2.55	1.20	4.0	4.0	2.0	8.0	Q3

- 1. All dimensions are nominal.
- 2. Plastic or metal protrusions of 0.15mm maximum per side are not included.



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